

1.9mm Round Subminiature “Yoke” Lead Infrared LED EAISY2021A1



Features

- Small double-end package
- High reliability
- Low forward voltage
- Good spectral matching to Si photo-detector
- Pb free
- The product itself will remain within RoHS compliant version.

Descriptions

EAISY2021A1 is an infrared emitting diode in miniature SMD package which is molded in a water clear plastic with spherical top view lens. The device is spectrally matched with silicon photodiode and phototransistor.

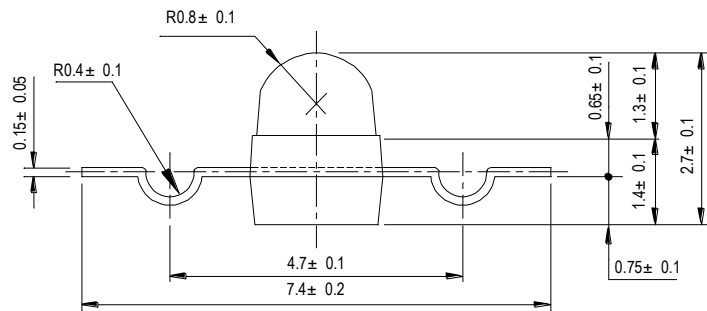
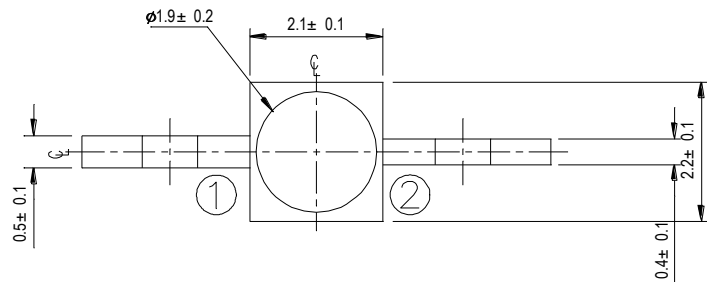
Applications

- PCB mounted infrared sensor
- Infrared emitting for miniature light barrier
- Floppy disk drive
- Printer

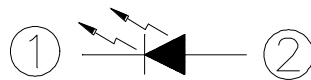
Device Selection Guide

Part Category	Chip Material	Lens Color
EAISY2021A1	GaAlAs	Water Clear

Package Dimensions



① Cathode



② Anode

- Notes:** 1.All dimensions are in millimeters
 2.Tolerances unless dimensions ± 0.1 mm

Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Rating	Units
Continuous Forward Current	I_F	65	mA
Reverse Voltage	V_R	5	V
Operating Temperature	T_{opr}	-40 ~ +85	°C
Storage Temperature	T_{stg}	-40 ~ +100	°C
Soldering Temperature	T_{sol}	260	°C
Power Dissipation at(or below) 25°C Free Air Temperature	P_d	130	mW

Notes: *1:Soldering time ≤ 5 seconds.

Electro-Optical Characteristics (Ta=25°C)

Parameter	Symbol	Condition	Min.	Typ.	Max.	Units
Radiant Intensity	I _e	I _F =20mA	3.0	5.0	--	mW/sr
		I _F =100mA Pulse Width ≤ 100 μs and Duty ≤ 1%	--	25	--	
Peak Wavelength	λ _p	I _F =20mA	--	940	--	nm
Spectral Bandwidth	Δλ	I _F =20mA	--	45	--	nm
Forward Voltage	V _F	I _F =20mA	--	1.2	1.5	V
		I _F =100mA Pulse Width ≤ 100 μs and Duty ≤ 1%	--	1.4	1.8	
		I _F =1A	--	2.6	4.0	
Reverse Current	I _R	V _R =5V	--	--	10	μA
View Angle	2θ 1/2	I _F =20mA	--	25	--	deg

Intensity Specifications for Bin Grading

Rank	Test Condition	Min	Max	Unit
J	I _F =20mA	3.0	4.5	mW/sr
K		4.0	6.0	
L		5.0	7.5	
M		6.0	9.0	
N		7.0	10.5	
P		8.0	12.0	
Q		9.0	13.5	
R		10.0	15.0	
S		11.0	16.5	
T		12.0	18.0	

Typical Electro-Optical Characteristics Curves

Fig.1 Forward Current vs. Ambient Temperature

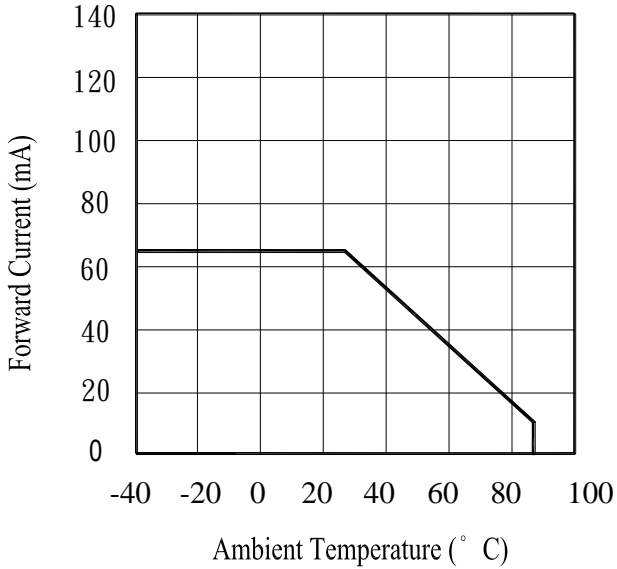


Fig.2 Spectral Distribution

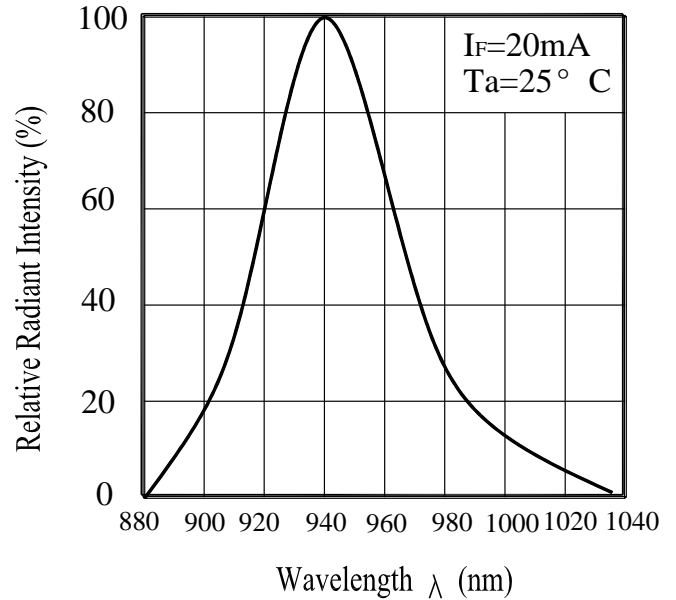


Fig.3 Peak Emission Wavelength vs. Ambient Temperature

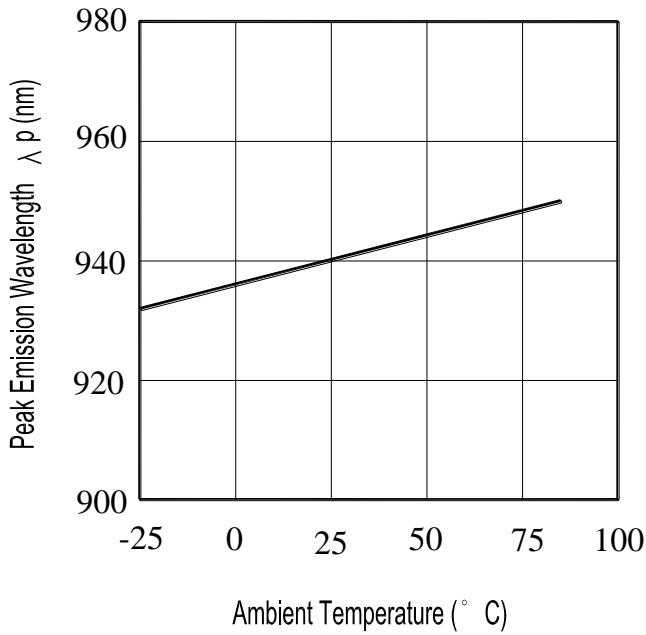
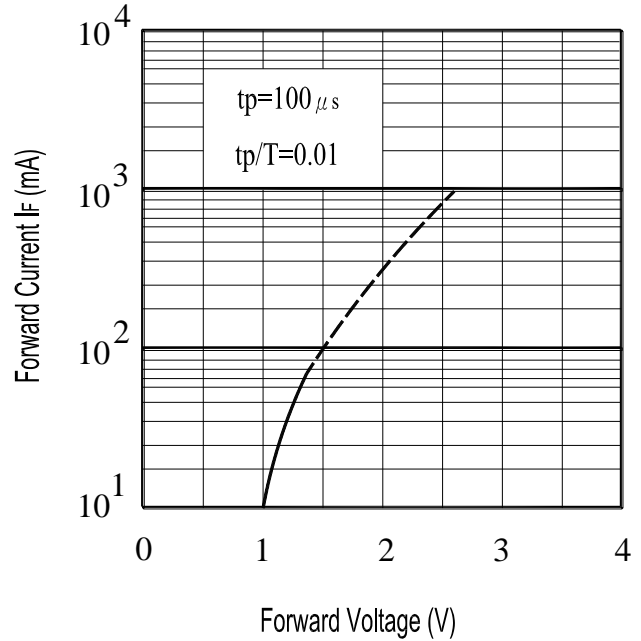


Fig.4 Forward Current vs. Forward Voltage



Typical Electro-Optical Characteristics Curves

Fig.5 Relative Intensity vs.
 Forward Current

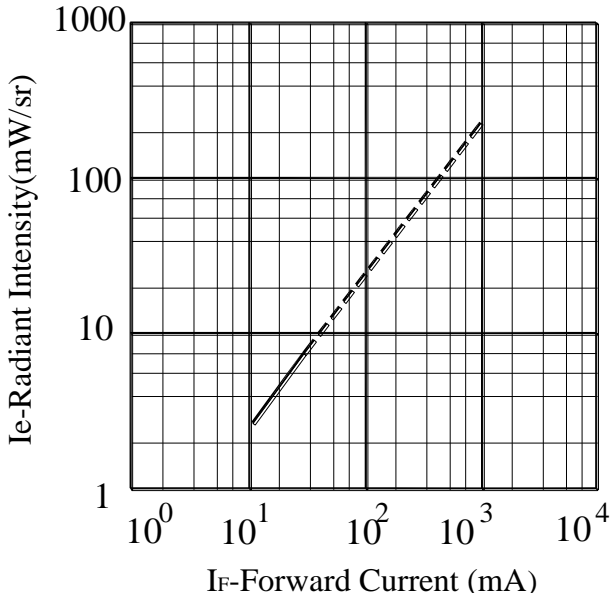


Fig.6 Relative Radiant Intensity vs.
 Angular Displacement

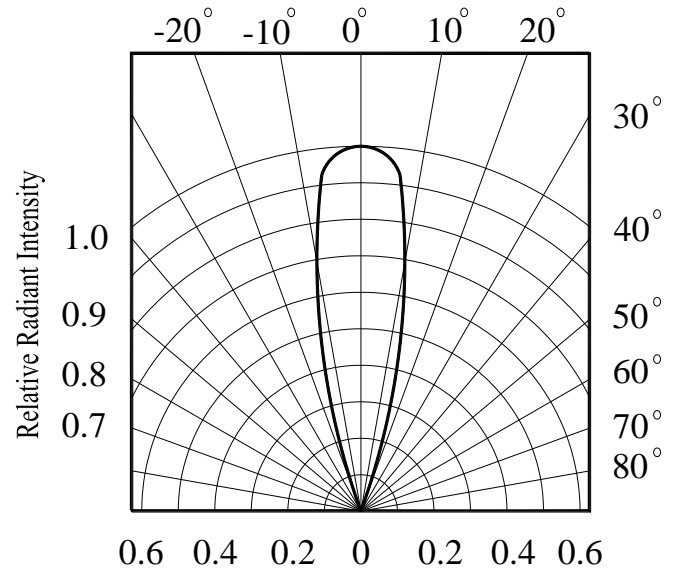


Fig.7 Relative Intensity vs.
 Ambient Temperature(° C)

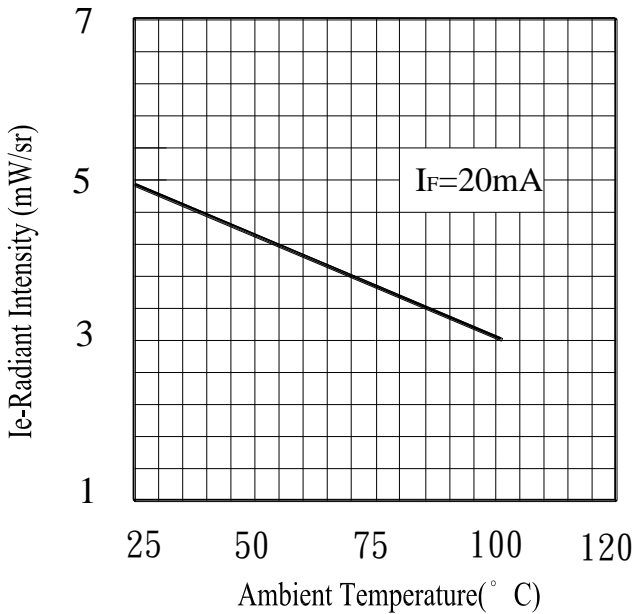
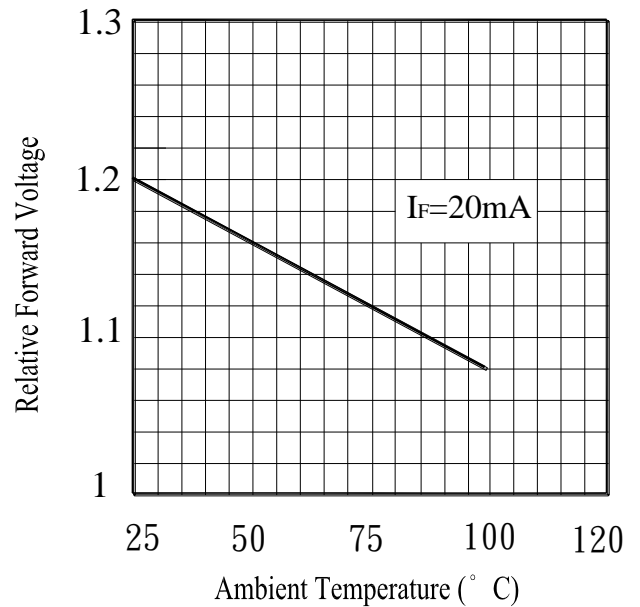


Fig.8 Forward Voltage vs.
 Ambient Temperature(° C)



Precautions For Use

1. Over-current-proof

Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change (Burn out will happen).

2. Storage

2.1 Do not open moisture proof bag before the products are ready to use.

2.2 Before opening the package: The LEDs should be kept at 30°C or less and 90%RH or less.

2.3 The LEDs should be used within a year.

2.4 After opening the package, the LEDs should be kept at 30°C or less and 60%RH or less.

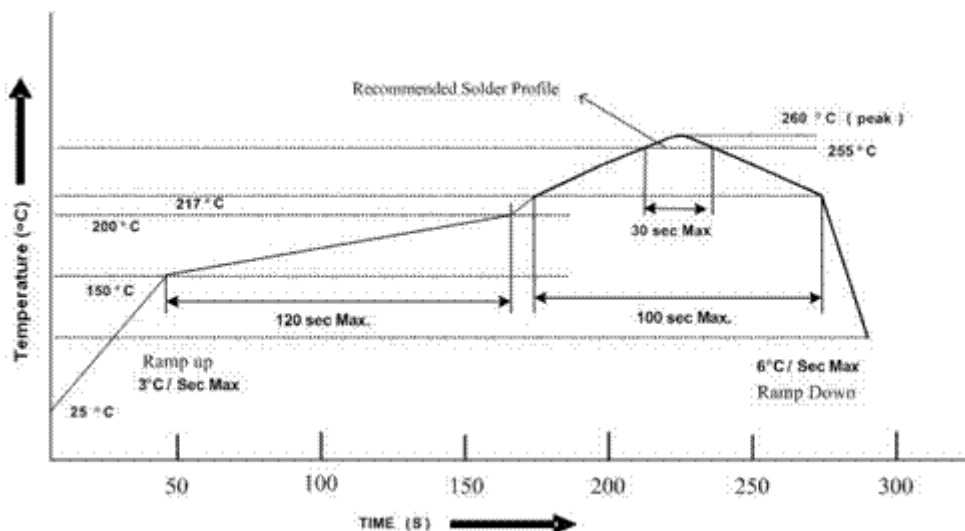
2.5 The LEDs should be used within 168 hours (7 days) after opening the package.

2.6 If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions.

Baking treatment : 60±5°C for 48 hours.

3. Soldering Condition

3.1 Pb-free solder temperature profile



3.2 Reflow soldering should not be done more than two times.

3.3 When soldering, do not put stress on the LEDs during heating.

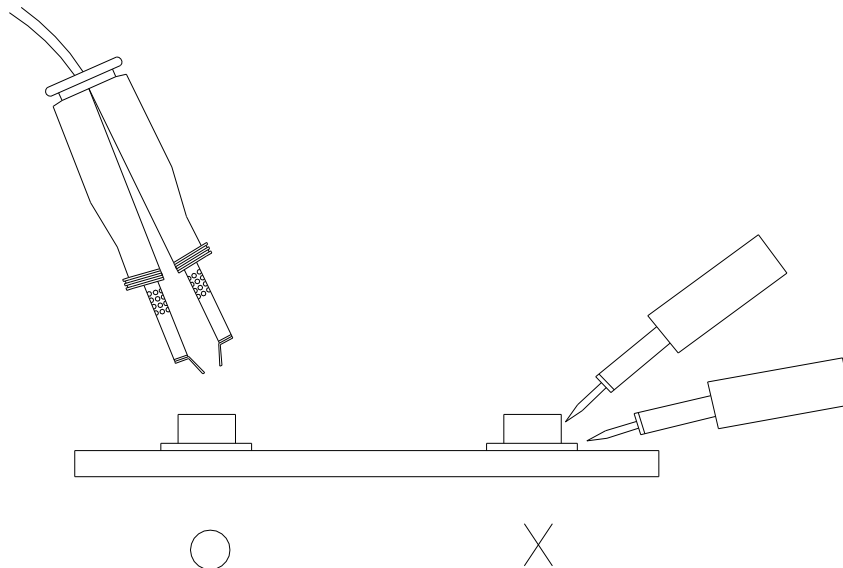
3.4 After soldering, do not warp the circuit board.

4. Soldering Iron

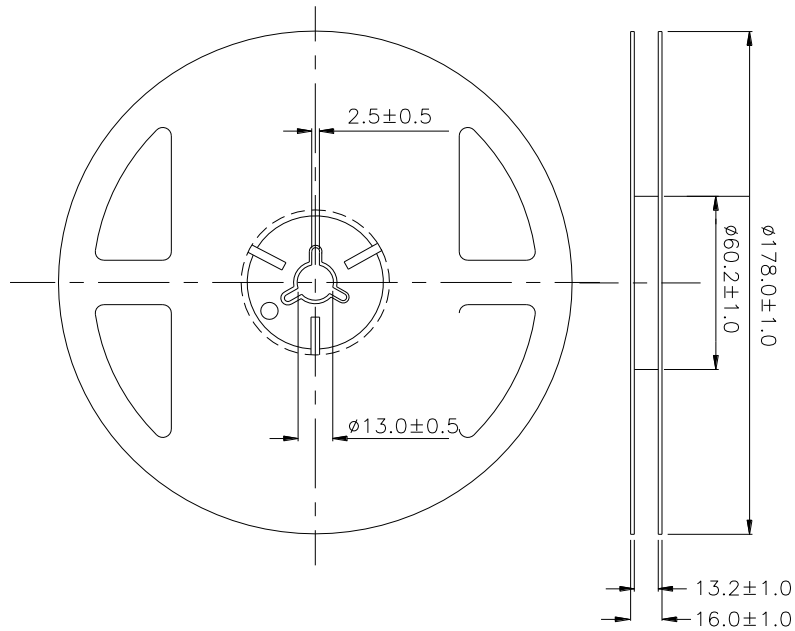
Each terminal is to go to the tip of soldering iron temperature less than 350°C for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

5. Repairing

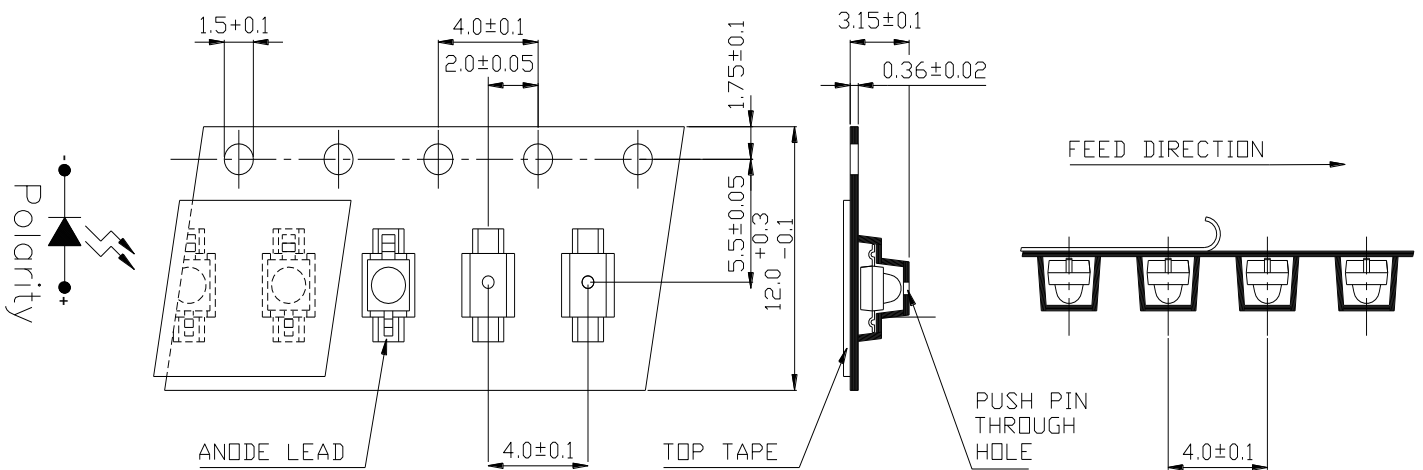
Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.



Package Dimensions



Carrier Taping Dimensions: Loaded Quantity Per Reel 1000PCS/Reel



Note: The tolerances unless mentioned is ± 0.1 mm, Unit = mm

Label Form Specification

Pb EVERLIGHT AMERICA

CPN: XXXXXXXXXXXX
P/N: XXXXXXXXXXXX

XXXXXXXXXXXXXXXXXXXX

QTY: XXXX CAT: XXX
HUE: XXX
REF: XXX

LOT NO: XXXXXXXXXXXXXXXXXXXX

XXXXXXXXXXXXXXXXXXXX

REFERENCE: XXXXXXXXXXXX

XXXXXXXXXXXXXXXXXXXX

MADE IN TAIWAN

CPN: Customer's Production Number

P/N : Production Number

QTY: Packing Quantity

CAT: Ranks

HUE: Peak Wavelength

REF: Reference

LOT No: Lot Number

Notes

1. Above specification may be changed without notice. Everlight Americas will reserve authority on material change for above specification.
2. When using this product, please observe the absolute maximum ratings and the instructions for using outlined in these specification sheets. Everlight Americas assumes no responsibility for any damage resulting from use of the product which does not comply with the absolute maximum ratings and the instructions included in these specification sheets.
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